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MacDermid Alpha to Promote High Reliability Die Attach Solutions at PCIM, Nuremberg

(Waterbury, CT USA) – April 18th, 2019 – The Assembly division of MacDermid Alpha Electronics Solutions, the world leader in the production of electronics soldering and bonding materials, will showcase its range of high reliability die attach solutions, including ALPHA® Argomax® Silver Sinter Technology, at the PCIM exhibition in Nuremberg, Germany from the 7th- 9th May 2019.

During the show, Gyan Dutt, Global Portfolio Manager, Die Attach Assembly for MacDermid Alpha, will be presenting on the “Thermal Resistance of Interconnect Layers in Inverter Power Assembly Stacks” at the PCIM Conference. “The increasing adoption of wide band gap semiconductors, along with the increasing current density within the power modules in traction inverters, has led to the thermal impedance of the stack becoming more important” comments Gyan. “The paper presentation will look at the role of interconnects in power assembly stacks and how this effects the overall thermal resistance.”

[ALPHA® Argomax® Silver Sinter Technology](#), which has been specially developed for die attach, package attach and substrate-heat spreader attach in traction inverters and other high voltage applications, provides a dramatic reduction in thermal resistance and inductance.

“The ALPHA® Argomax® technology creates extremely high thermal and electrical conductivity silver bonds”, explains Julien Joguet, Global Business Market Manager, Die Attach at MacDermid Alpha. “The high thermal conductivity delivered by ALPHA® Argomax® enables individual die to handle much higher levels of current, reducing the total number of die required, and providing the highest levels of efficiency. ALPHA® Argomax® also provides an unprecedented increase in die attach reliability, more than 30x higher than traditional solder methods.”

ALPHA® Argomax® is available in paste, film and preform material types and solutions from Ag, Au and Cu surface finishes for unparalleled flexibility. To speak to one of our technology experts visit MacDermid Alpha in Hall 7 Booth 518 at the PCIM exhibition or visit the [Alpha website](#).

About PCIM

Date: Tuesday 7th – Thursday 9th May

Location: Nuremberg, Germany

PCIM Europe (Power Conversion and Intelligent Motion) is the international leading exhibition for Power Electronics, Intelligent Motion, Renewable Energy and Energy Management. Exhibitors from across the globe will present the newest products, trends and developments in the power electronics industry. PCIM Europe is the forum for technologies for the whole value chain of the power electronics industry from the components to the intelligent system.

<https://pcim.mesago.com/events/en.html>

About MacDermid Alpha Electronics Solutions

Through the innovation of specialty chemicals and materials under our Alpha, Compugraphics, and MacDermid Enthone brands, MacDermid Alpha Electronics Solutions provides solutions that power electronics interconnection. We serve all global regions and every step of device manufacturing within each segment of the electronics supply chain. The experts in our Semiconductor Solutions, Circuitry Solutions, and Assembly Solutions divisions collaborate in design, implementation, and technical service to ensure success for our partner clients. Our solutions enable our customers' manufacture of extraordinary electronic devices at high productivity and reduced cycle time. Find more at MacDermidAlpha.com.

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